

# Week 2-12

## Thin Film Transistors 3

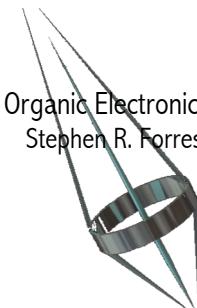
Self-assembled monolayers

Threshold voltage drift

Applications

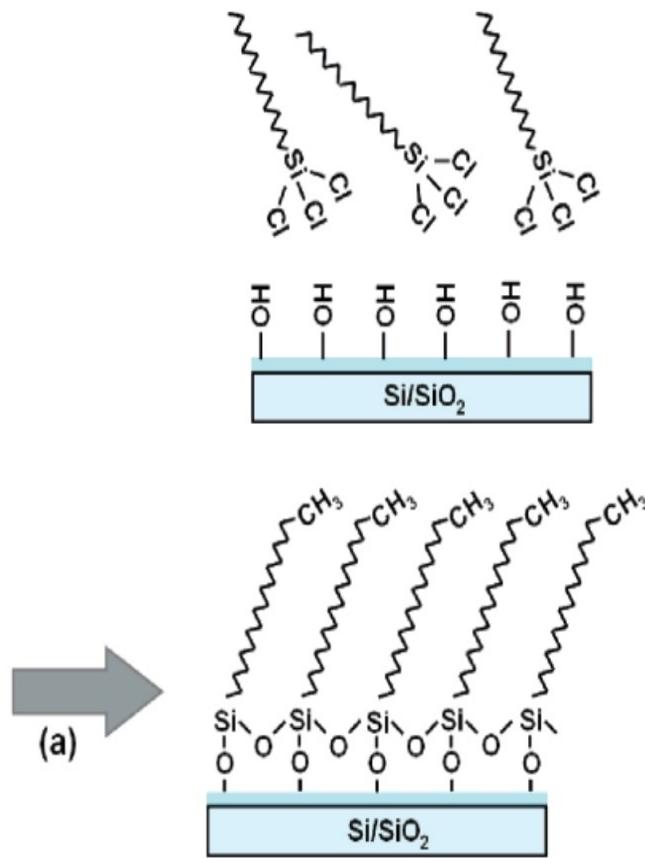
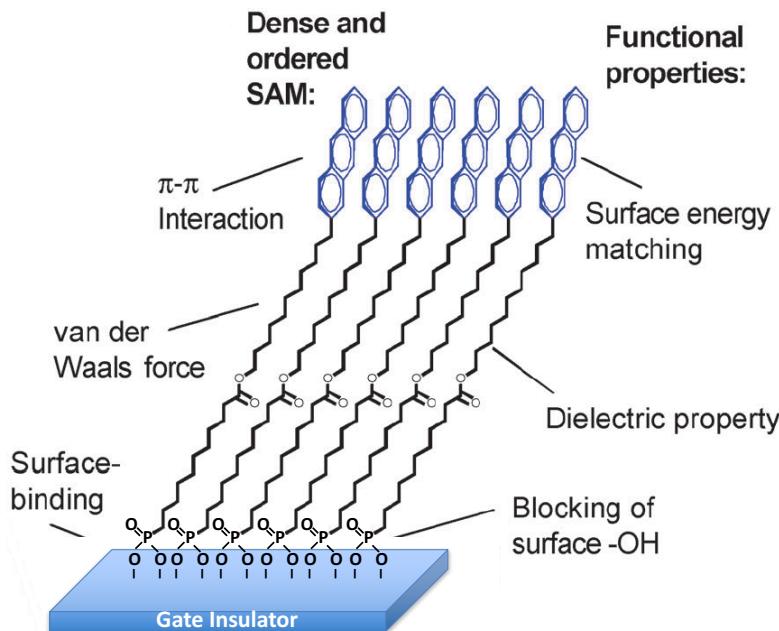
Chapter 8.6.1, 8.7-8.9

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# Achieving Optimal Morphologies

- Method 1: Control during growth by VTE, OVPD, solution
- Method 2: Use Self Assembled Monolayer (SAM) functionalization to initiate growth of desired structures by vapor or solution deposition

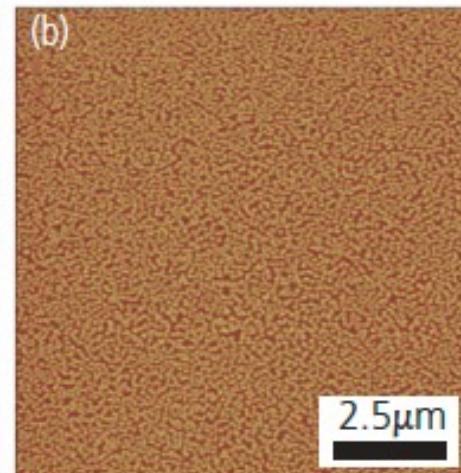
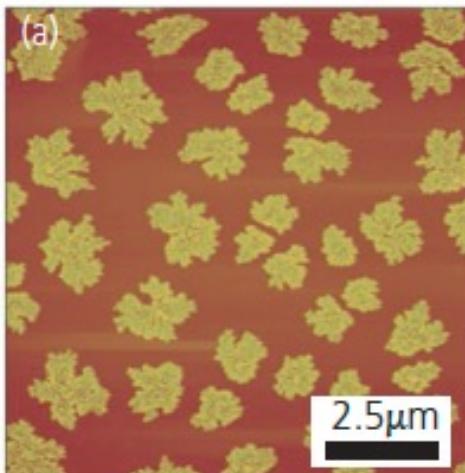


Example: Octyltrichlorosilane (OTS)<sub>2</sub>

# Very Different Film Morphologies Achieved Depending on Surface Preparation

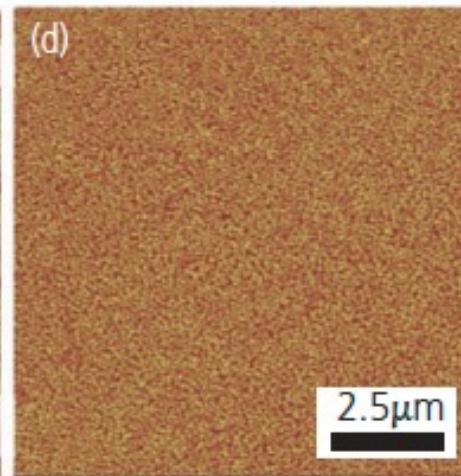
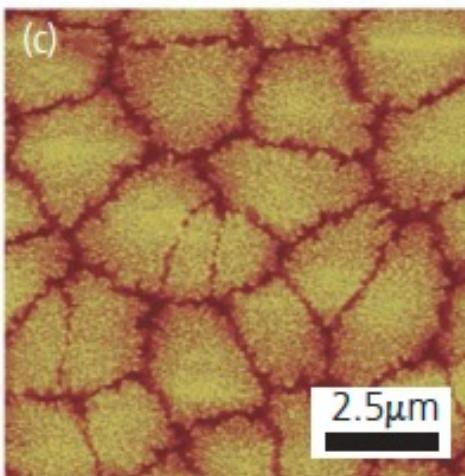
Organic semiconductor: VTE deposited C<sub>60</sub>

ML thick C<sub>60</sub> on  
ODPA on HfO<sub>2</sub>



ML thick C<sub>60</sub> on HfO<sub>2</sub>

50 nm C<sub>60</sub> on  
ODPA on HfO<sub>2</sub>



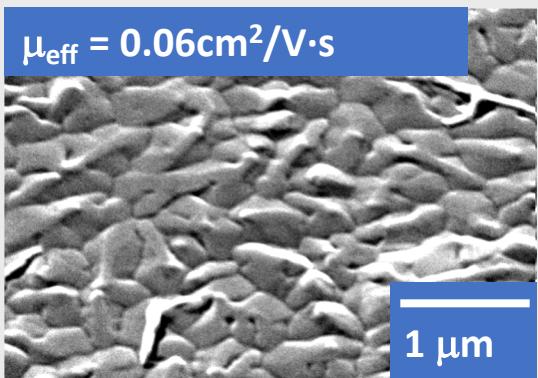
50 nm C<sub>60</sub> on HfO<sub>2</sub>

Larger grains on SAMs due to improved molecular surface mobility  $\Rightarrow$  clustering

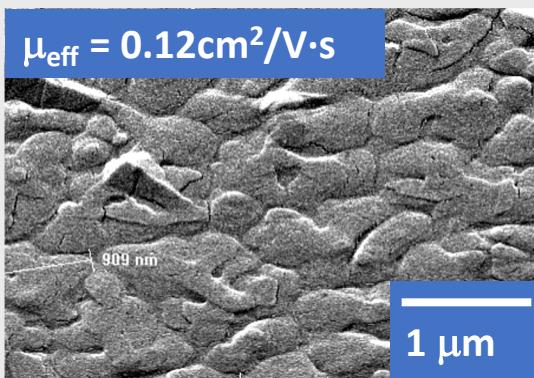
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# Controlling Pentacene Channel Morphology

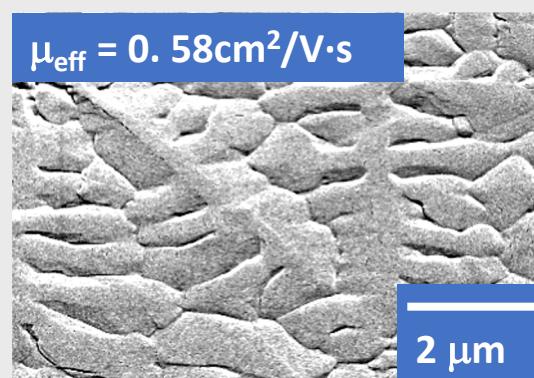
## OVPD growth



10° C, 0.25 Torr, 3.0 Å/s

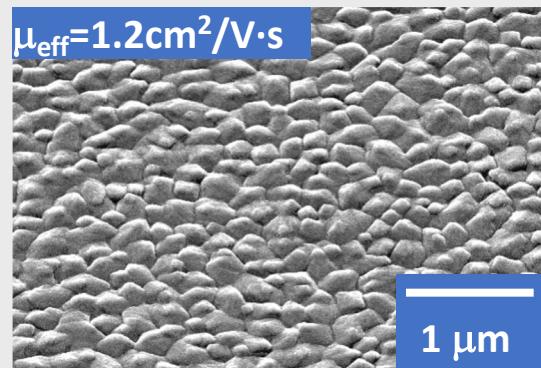


40° C, 6.0 Torr, 1.0 Å/s

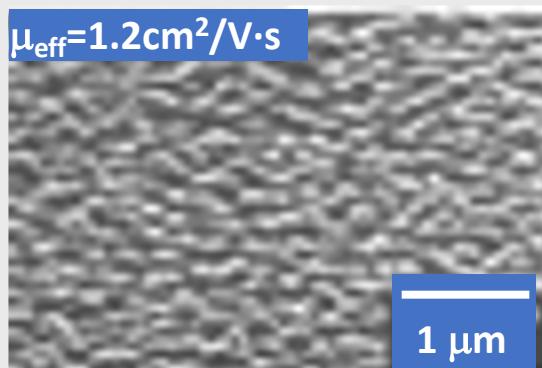


65° C, 10.5 Torr, 0.3 Å/s

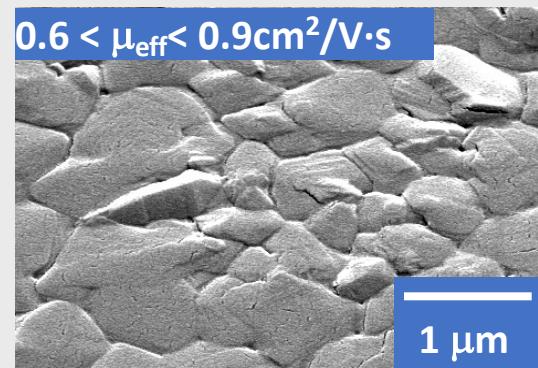
## Pentacene on OTS-SAM treated $\text{SiO}_2$



10° C, 0.25 Torr, 3.0 Å/s



40° C, 6.0 Torr, 1.0 Å/s



65° C, 10.5 Torr, 0.3 Å/s

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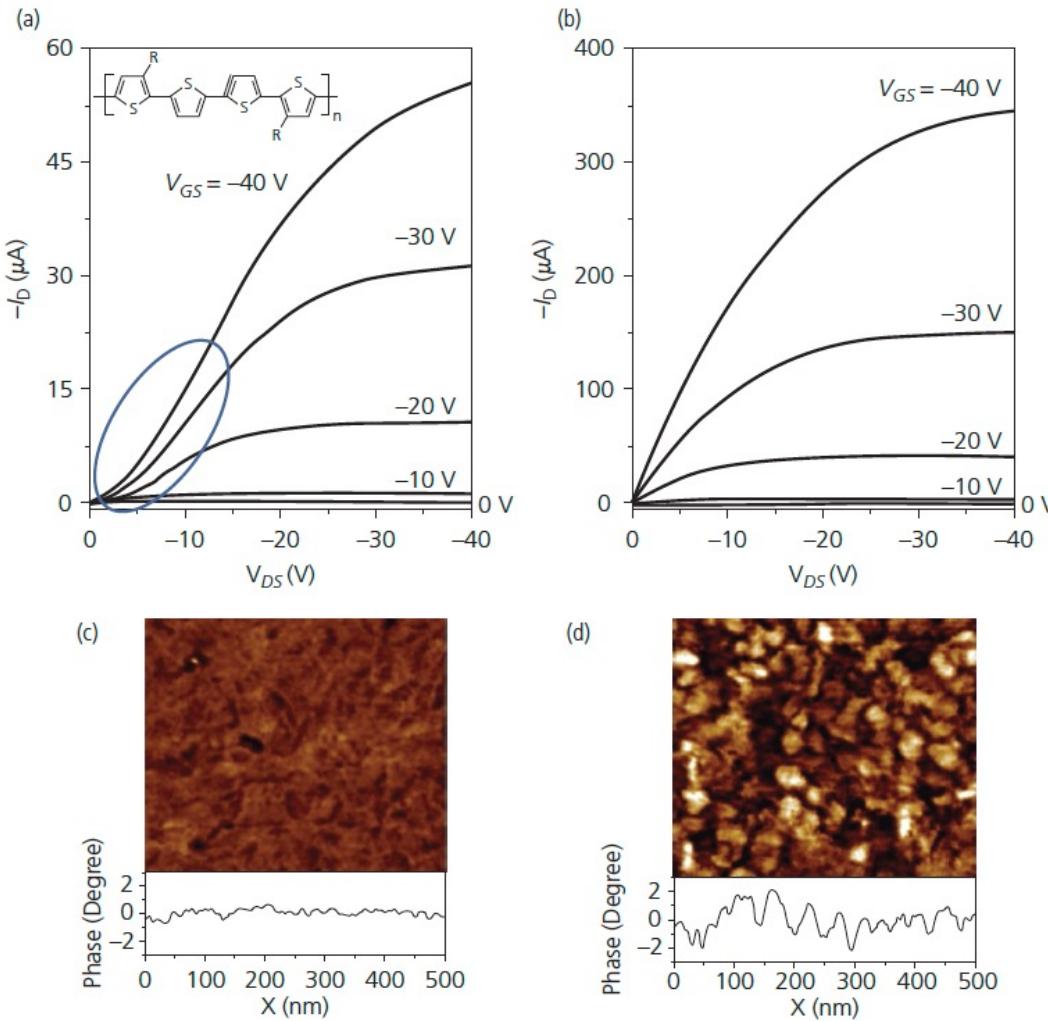


toward equilibrium

# Functionalizing Metal Surfaces Can Reduce Contact Resistance



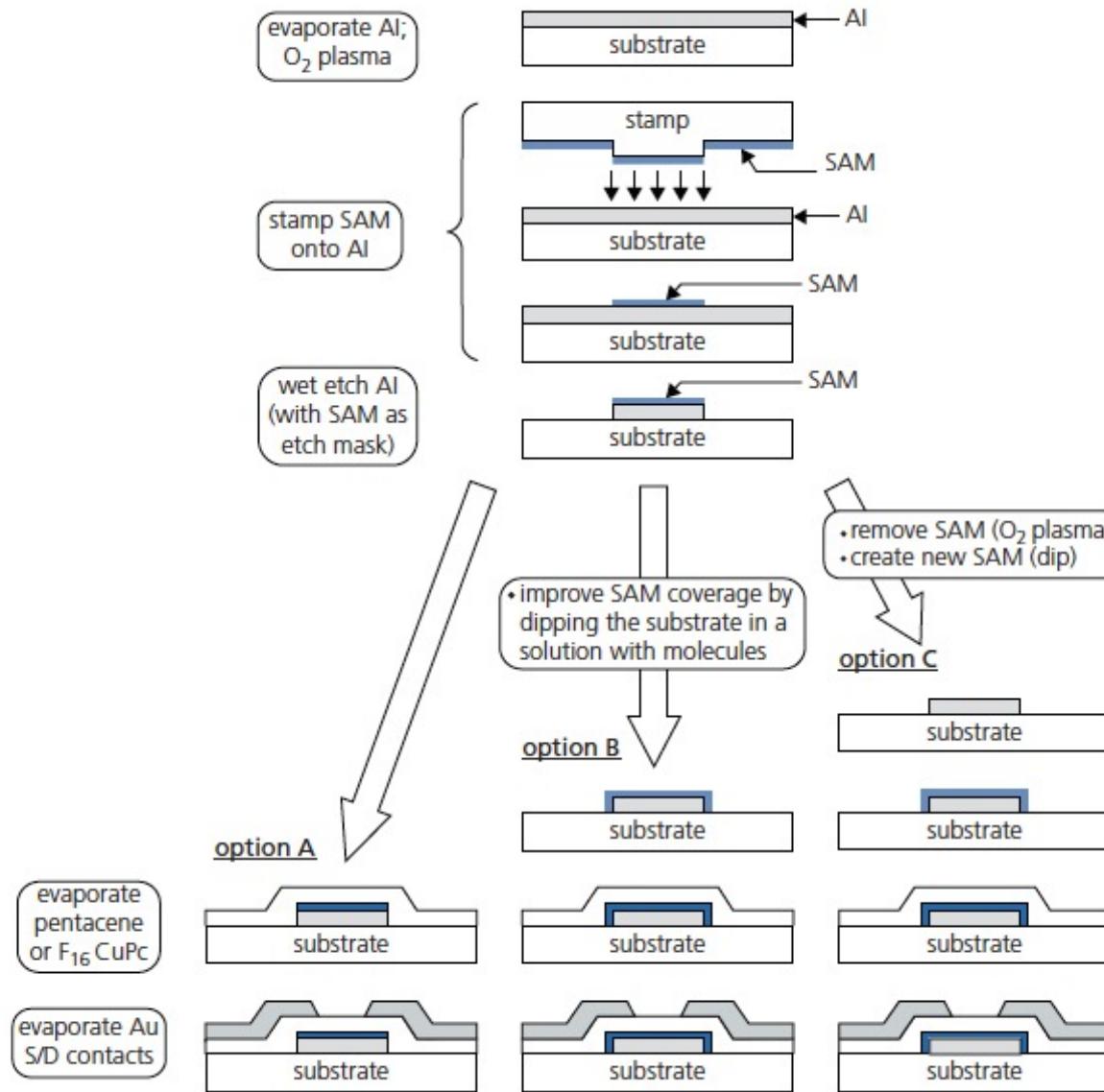
- Alkane thiols stick to Au via S-Au bond
- Alkane anchors subsequently deposited organic channel



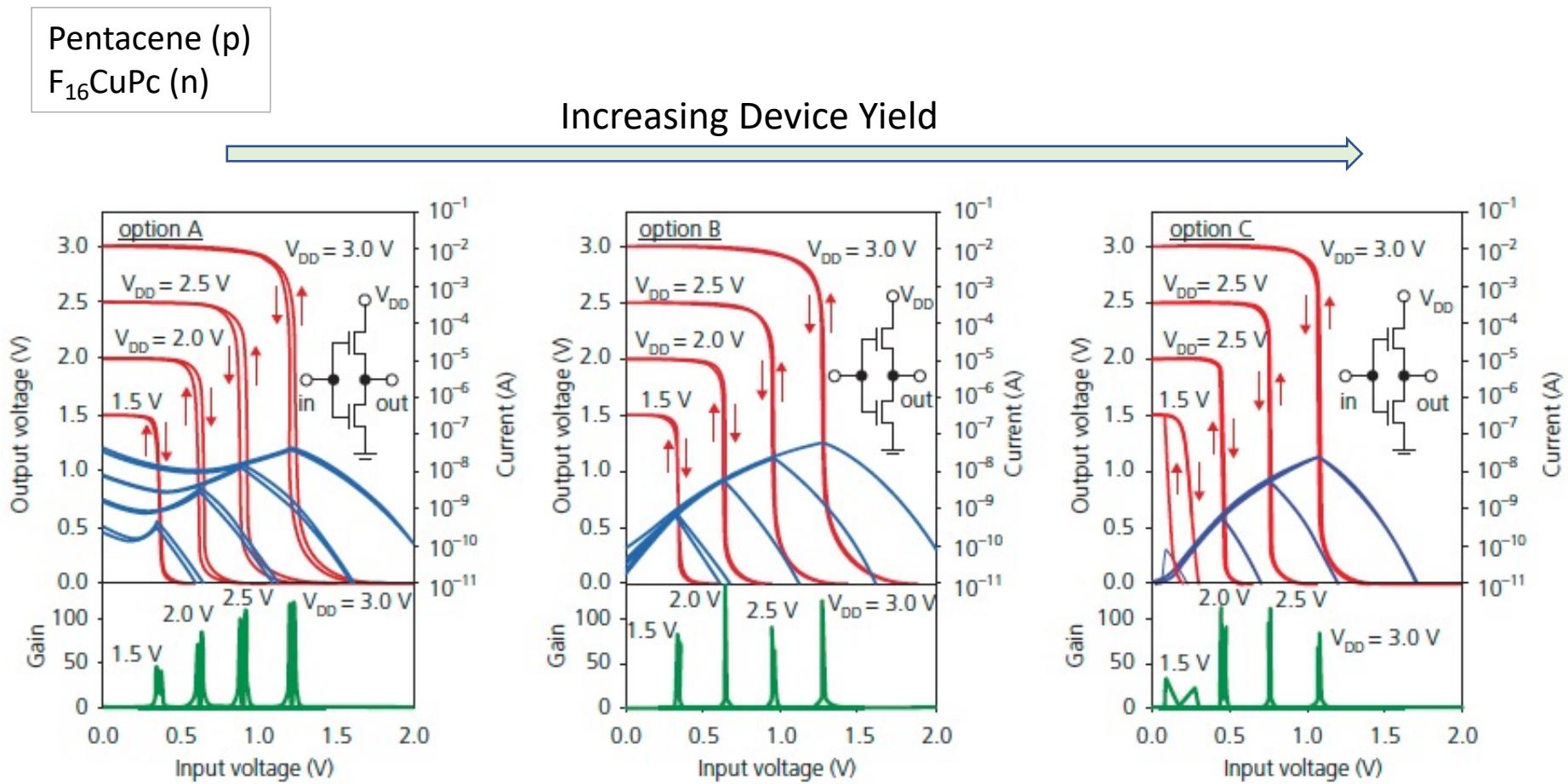
Large series resistance (oval region) in untreated substrate (left)  
Crystalline grains form on treated substrate (right) with lower  $R_C$

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# Contact Printing Initiated by SAM



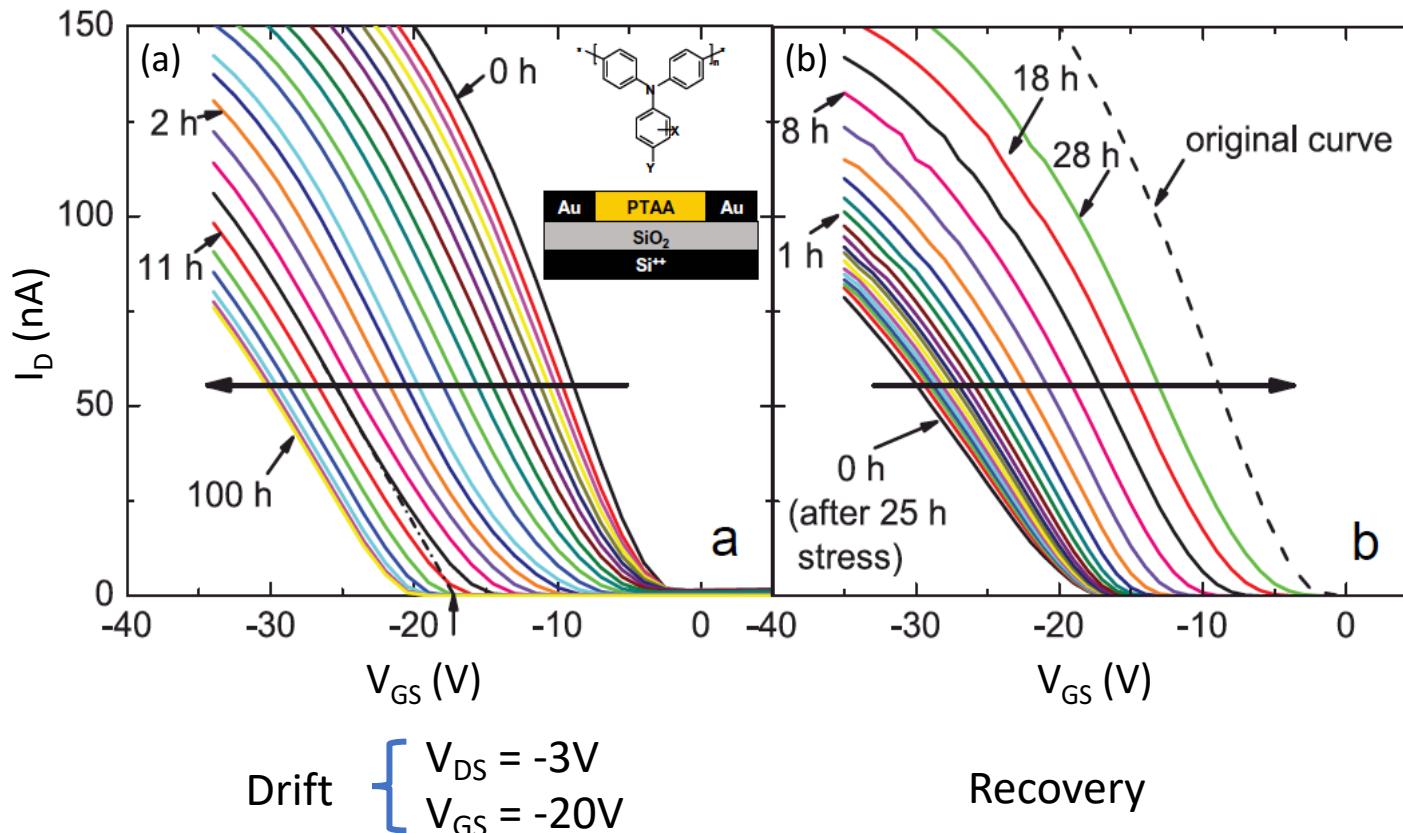
# Results vs. Deposition Process



Operating characteristics not strongly dependent on process

# Reliability

- Threshold voltage drift the primary source of circuit failure
  - Decreasing noise margin
  - Increasing leakage



Original transfer characteristics (and  $V_T$ ) partially recovered following stress

# Threshold voltage drift over time

(see Ch. 6.7 & 7.8)

- Drift due to charges migrating in insulator or channel toward the interface
  - Surface traps at the channel
  - Traps within the semiconductor bulk
  - Charge (ions) drifting within the insulator

$$\Delta V_T(t) = \Delta V_T(\infty) \left( 1 - \exp\left(-\frac{t}{\tau}\right)^m \right)$$

Empirical voltage drift expression:  
Stretched exponential

$m = T/T_0$  for exponential trap distribution given by:

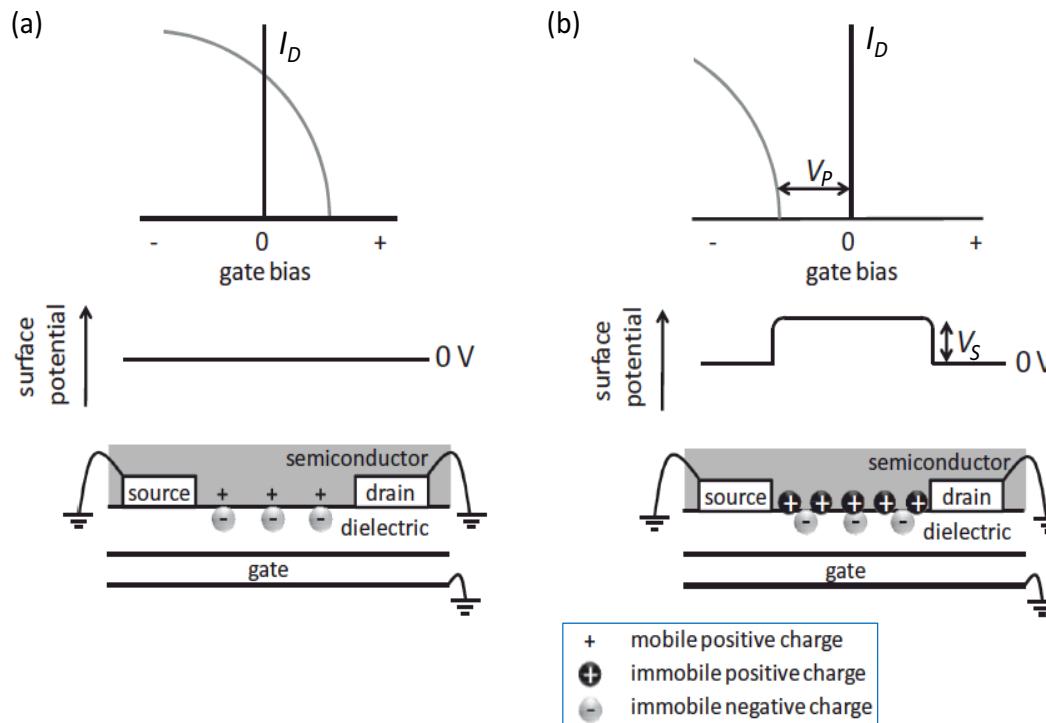
$$h_{tr}(E) = h_{tr0} \exp(-E/E_T)$$

⇒ Time constant for drift

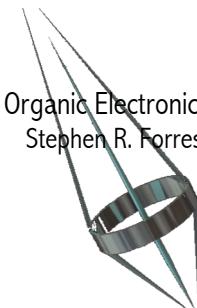
$$\tau = (2\pi\nu)^{-1} \exp(E_T/k_B T)$$

Drift occurs over an extended time, and is thermally activated

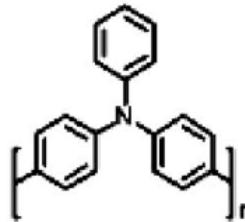
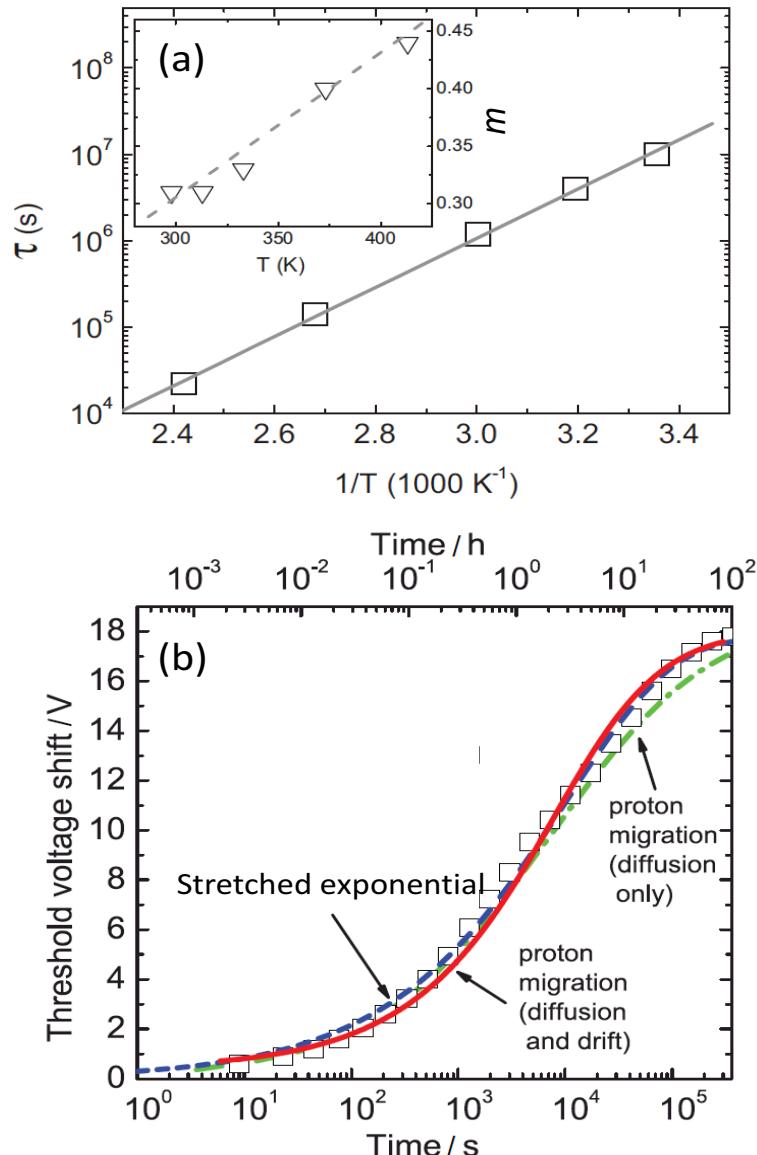
# Water/Proton Generation Drift Model



Protons at insulator interface shift the threshold voltage



# Comparing Proton Model to $\Delta V_T$

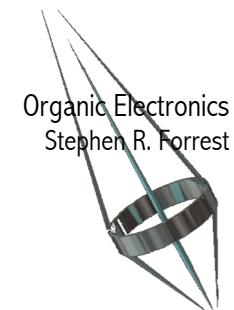


Example: Poly(triarylamine)

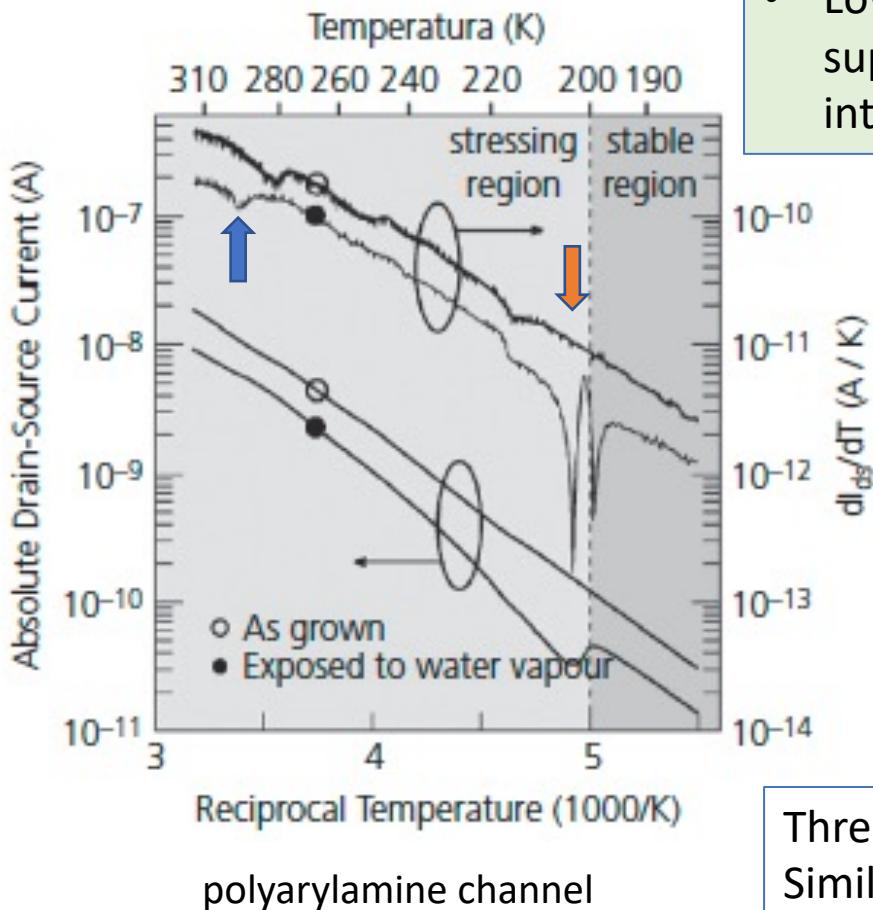
The voltage drift time constant:

- Follows the stretched exponential
- Is thermally activated with  $E_T = 0.6$  eV

Threshold voltage is fit assuming proton diffusion and drift in the field under the gate



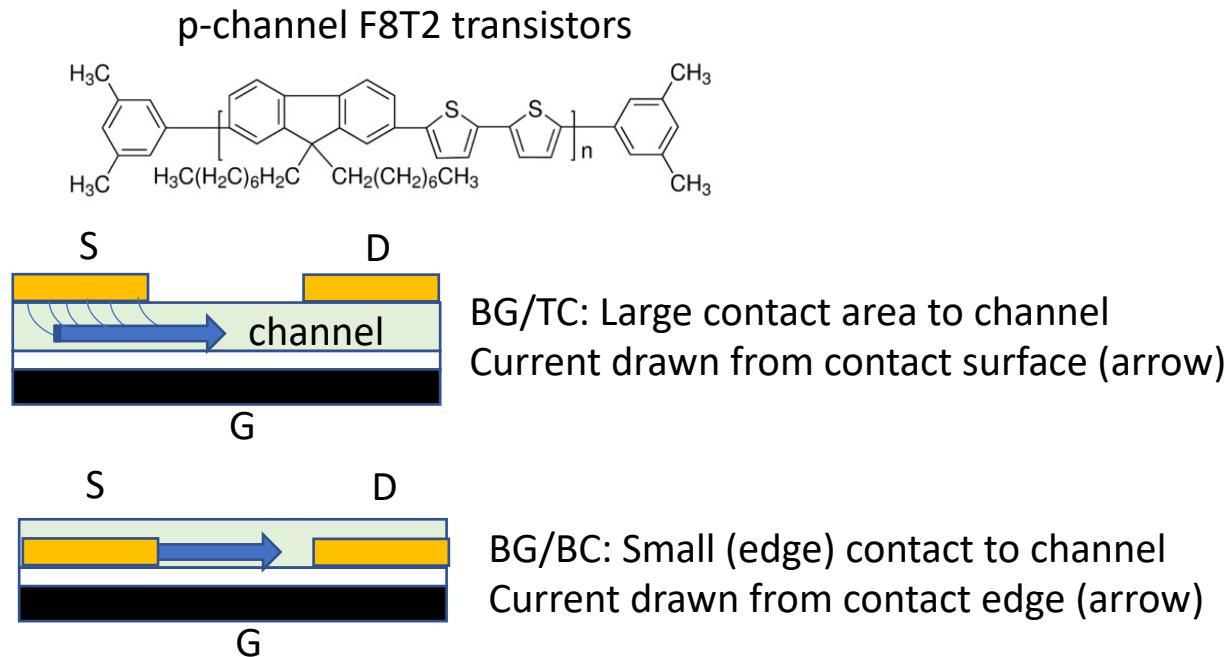
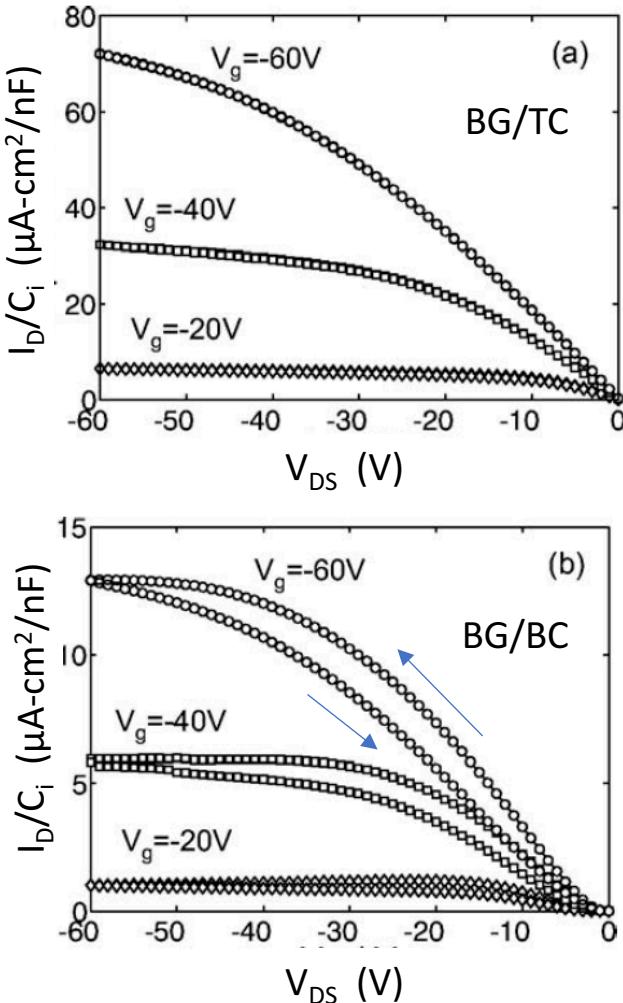
# Evidence for H<sub>2</sub>O at the Insulator Interface



- Change in drain current exposed to water shows peaks near 0°C and 205°C
- Low temperature peak due to freezing of supercooled H<sub>2</sub>O clusters confined at the insulator interface

Threshold drifts can be reduced by encapsulation  
Similar stability improvements in packaged devices  
also observed for OLEDs and OPVs

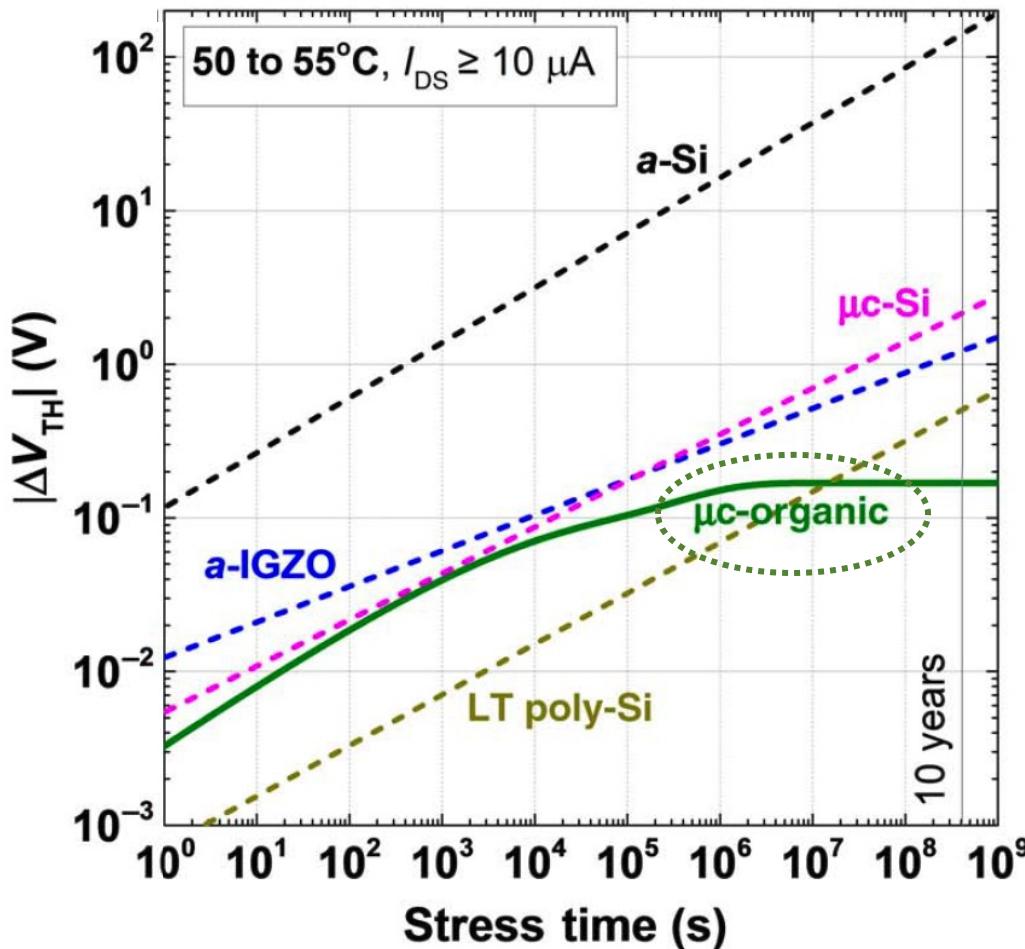
# Hysteresis: Another failure mode



## Drain contact trapping

Contact only via edge of the electrodes increases the current density, resulting in defect formation and charge trapping. This induces changes in  $V_T$  and  $I_{DS}$ , depending on sweep direction (arrows).

# Comparison of TFT Reliabilities

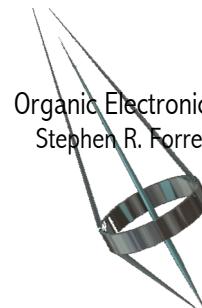


Jia, et al. Science Adv. 4, eaao1705, (2018)

Caveats (and there are many):

- Devices from different labs may be based on different standards and conditions
- Device selection not necessarily based on same characteristics
- Performance can vary over a wide range in any technology

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# Applications must exploit advantages, and cannot be vulnerable to disadvantages

To review....

- PROs
  - Flexible, conformable, ultralight
  - Can be made over very large areas
  - Suitable for large scale R2R manufacture
- CONS
  - Cannot source large currents
  - Characteristics drift over long periods in operation
  - Limited bandwidth ( $\leq 1$  MHz in many cases)

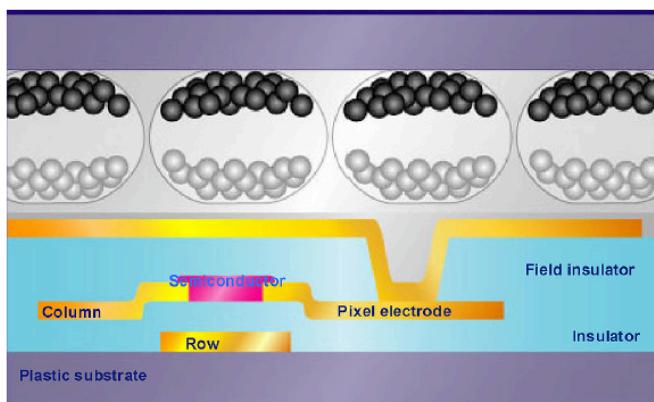
# Voltage driven display backplanes

- Electrophoretic displays



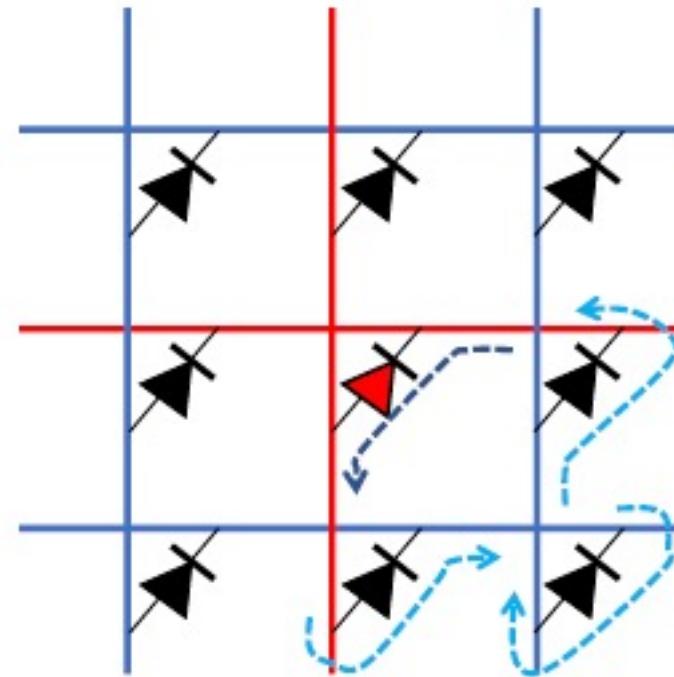
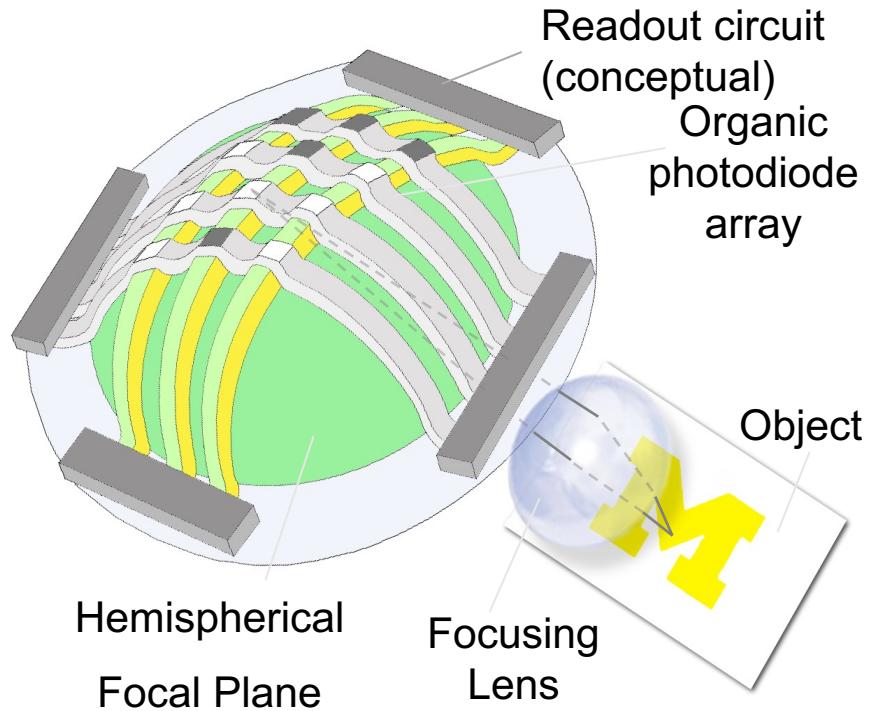
320 x 240 QVGA display  
Display pixels are voltage (not current) driven

QVGA=quarter video graphics array



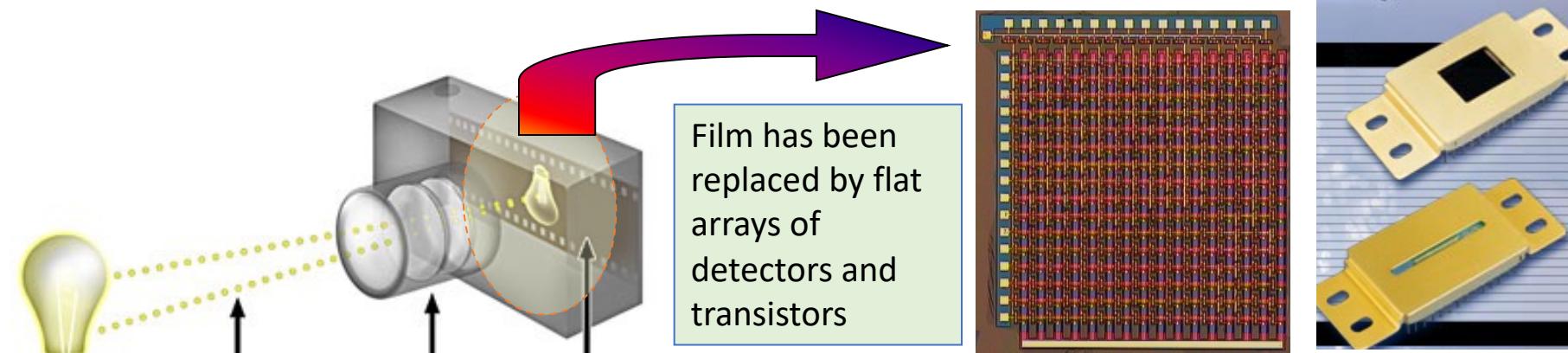
G. Gelinck *et al* J. Soc. Info. Display, 14, 113, 2006.

# Optical Detector Arrays



- Organics allow for fabrication on “non developable” surfaces: i.e. surfaces that cannot ordinarily be transformed from a plane without strain or distortion
- In Ch. 5 we showed that hemispherical focal plane arrays can be formed using the elastic properties of organics
- The FPA is in a passive matrix configuration
- “Sneak currents” (right) show that leakage from unaddressed detectors (black) can add to the photocurrent from the illuminated detector (red) in a passive matrix

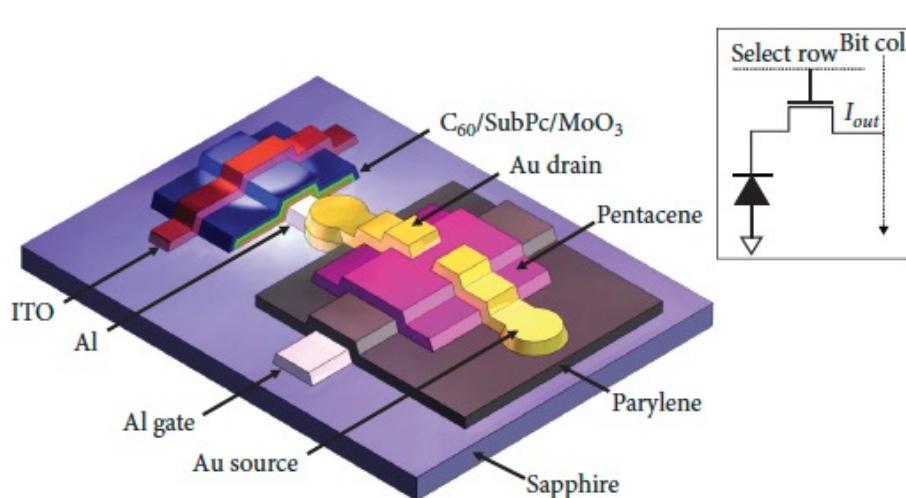
# Cameras vs. Eyes: A Comparison



Function	Eye	Camera
Focal Plane	Curved	Flat
Lens	Single element	Multiple element
Weight	Light	Heavy
Field of View (FOV)	180 °	Narrow~160 ° (w. distortion)
Lens speed	Fast	Slow
Size	~ 1 cm <sup>3</sup>	~200 cm <sup>3</sup>
Weight	gm's	Kg's

But the eye detection system is on an approximately hemispherical surface

# Transistor addressing circuits reduce sneak currents

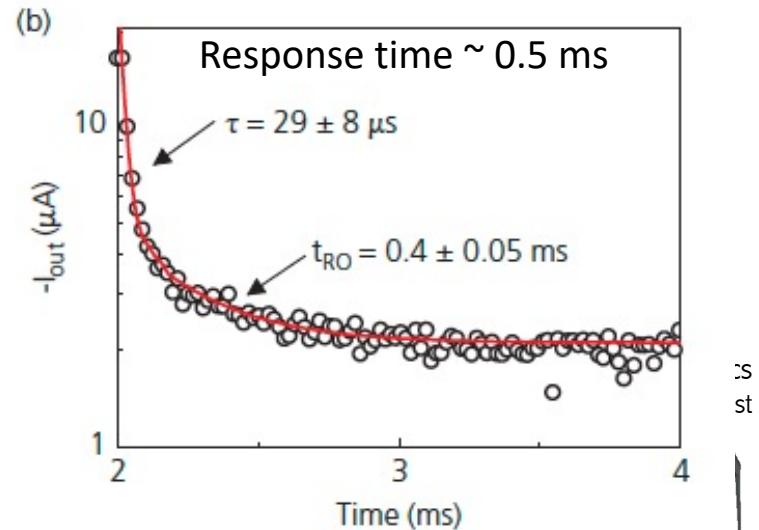
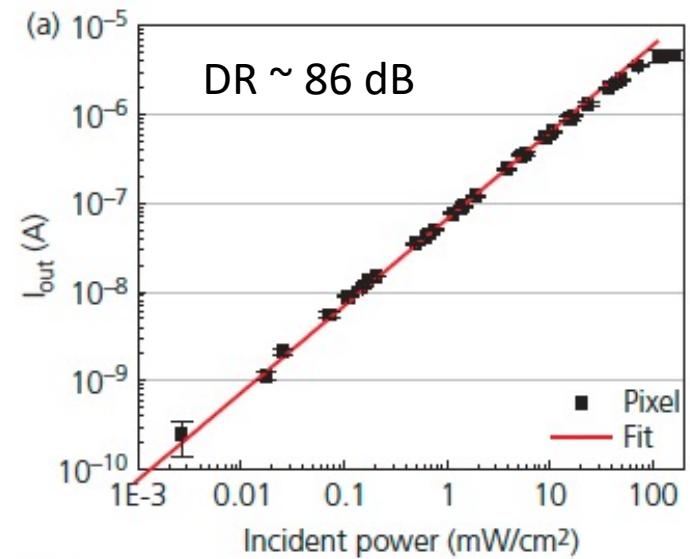


- One transistor address per pixel called passive pixel sensor
- Transistor used as switch to interrogate charge on photodiode in array
- Increases device dynamic range

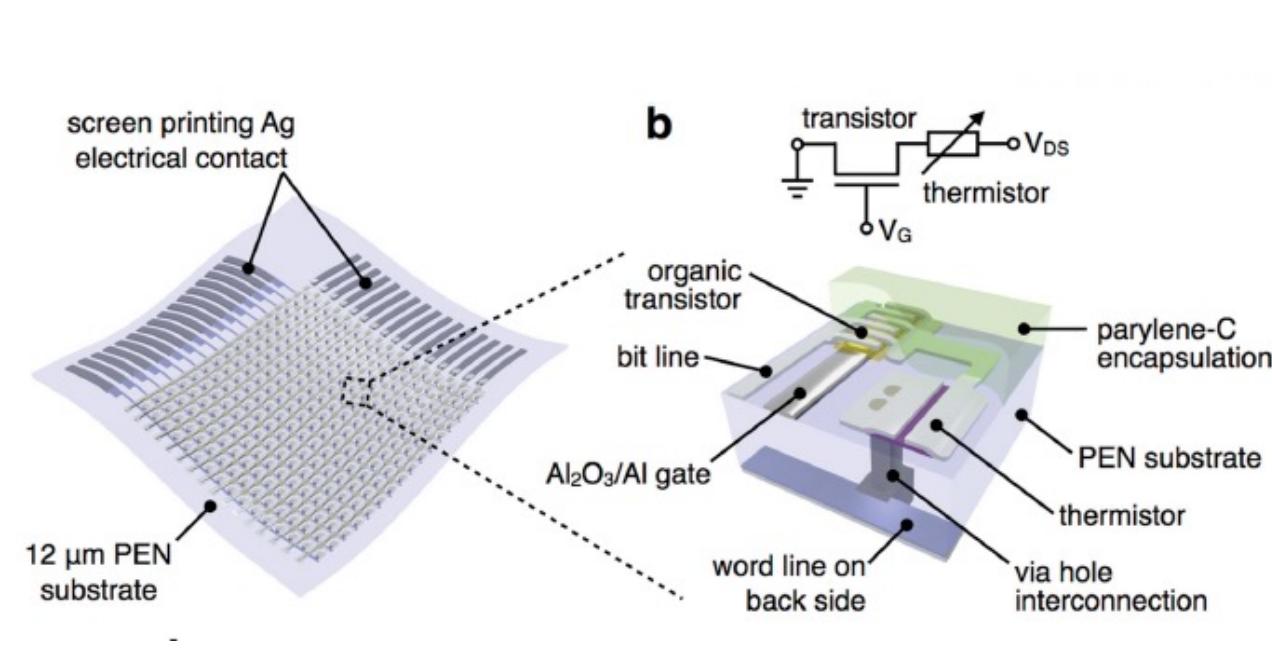
$$DR = 20 \log_{10} \left( \frac{I_{max}}{I_{min}} \right) [\text{dB}]$$

$I_{max}$  = max. photocurrent with < 1 dB distortion

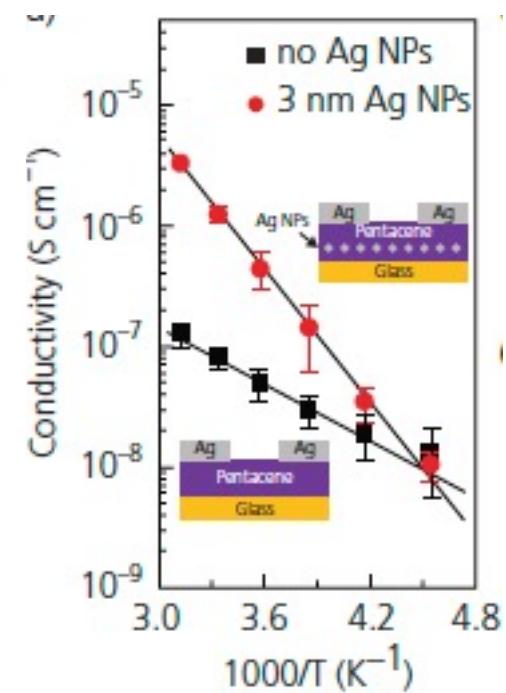
$I_{min}$  = min. detectable photocurrent with S/N = 1



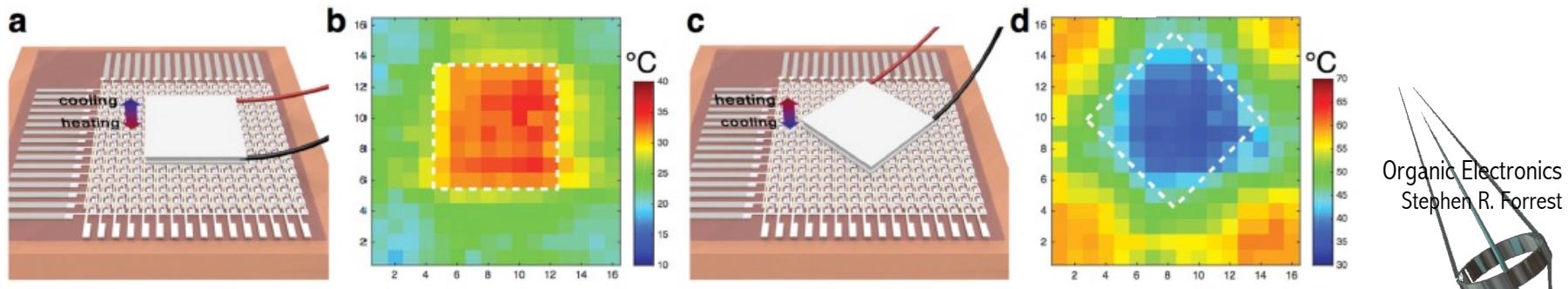
# Thermal Position Sensing



Array used for detecting position of thermal source



Sensing element: channel resistance with a Ag NP layer



# Chemical sensing

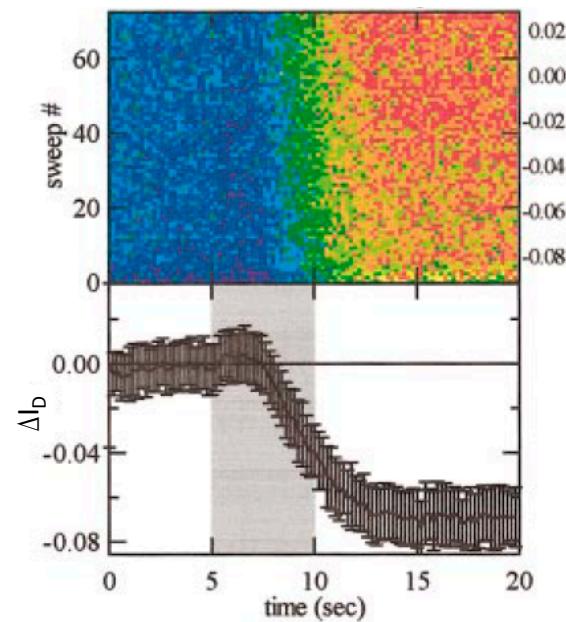
- OTFTs have demonstrated voltage drifts due to water.
- Are there other analytes that can be sensed?
- Sensor attributes
  - Fast
  - Sensitive to small doses
  - Reversible
  - Specific

$\alpha$ -6T transistor

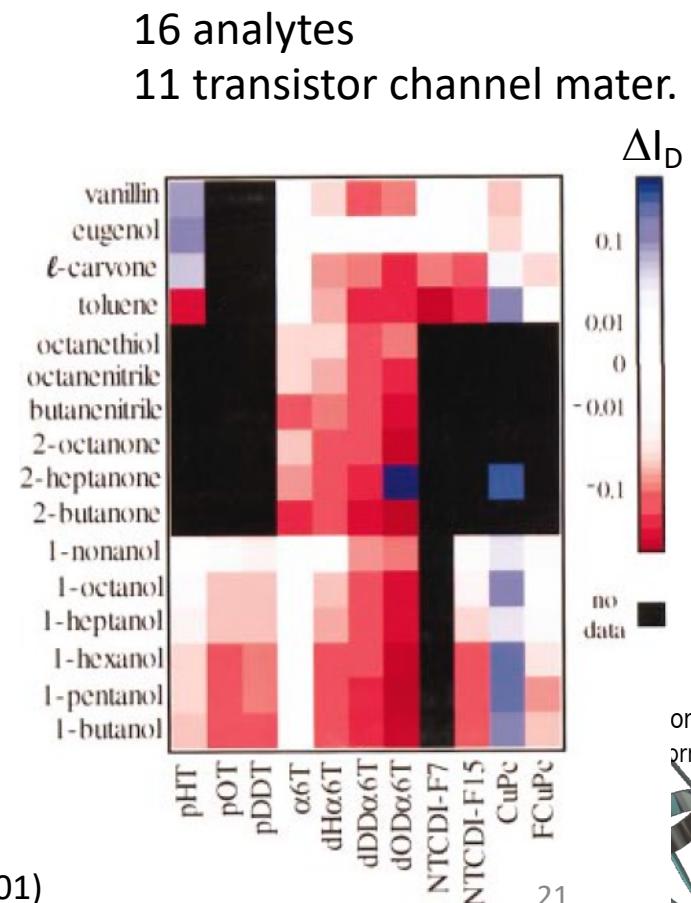
Analyte: 1-hexanol

Exposure: 5 s

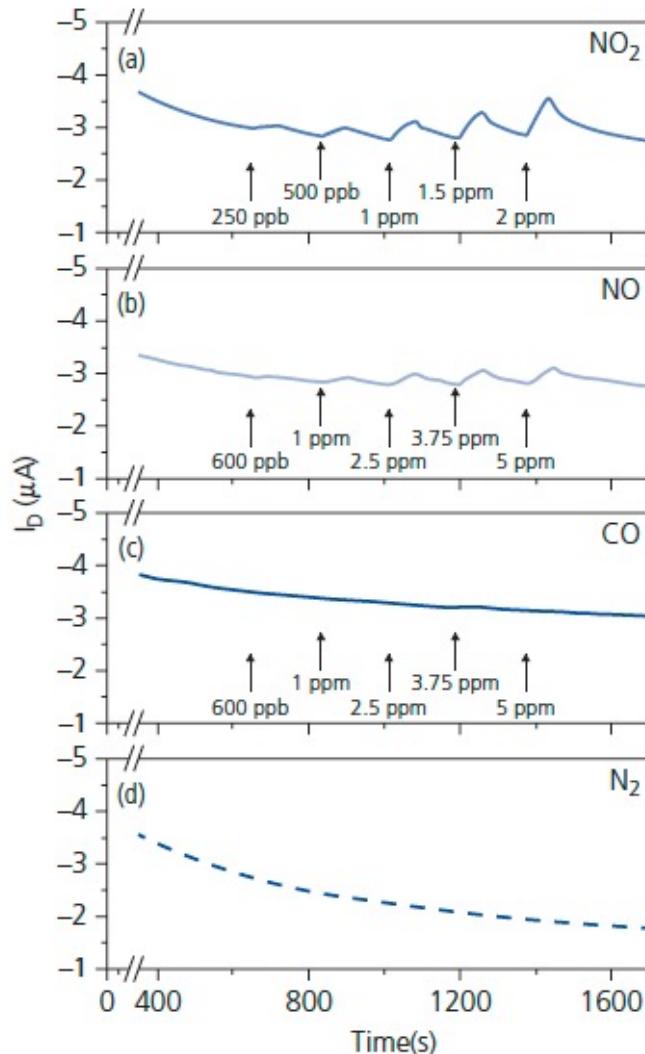
Recovery: 1 min



B. Crone *et al.*, 78, 2229, (2001)



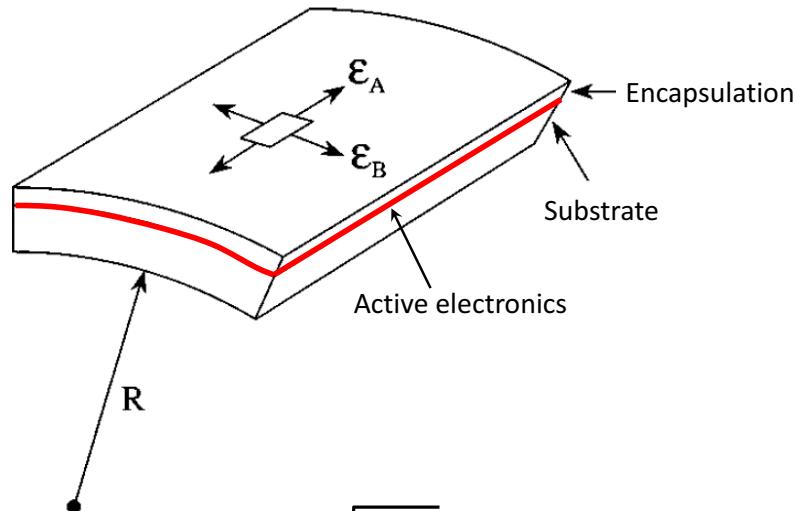
# Analyte-Specific Sensors Using D<sub>3A</sub> OTFT



- Highly sensitive (ppm)
- Specific to  $\text{NO}_2$  and  $\text{NO}$
- $\text{N}_2$  transient provides “no analyte” background

# Bendable Electronics

Placing active electronics at the neutral strain point  
⇒ minimal stress to circuits on bending even over sharp angles

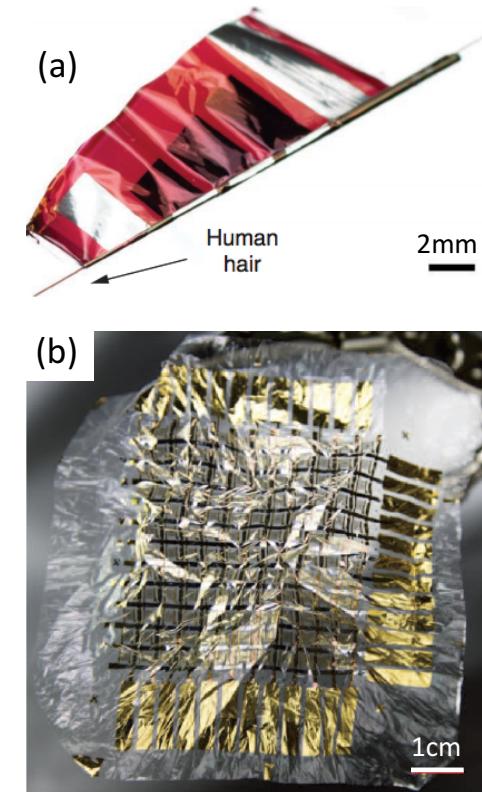


Neutral strain: 
$$\frac{d_{sub}}{d_e} = \sqrt{\frac{Y_e}{Y_{sub}}}$$

$Y$  = Young's modulus (measure of material stiffness)

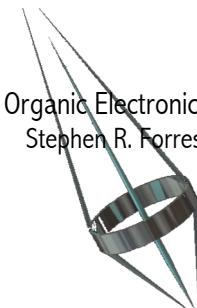
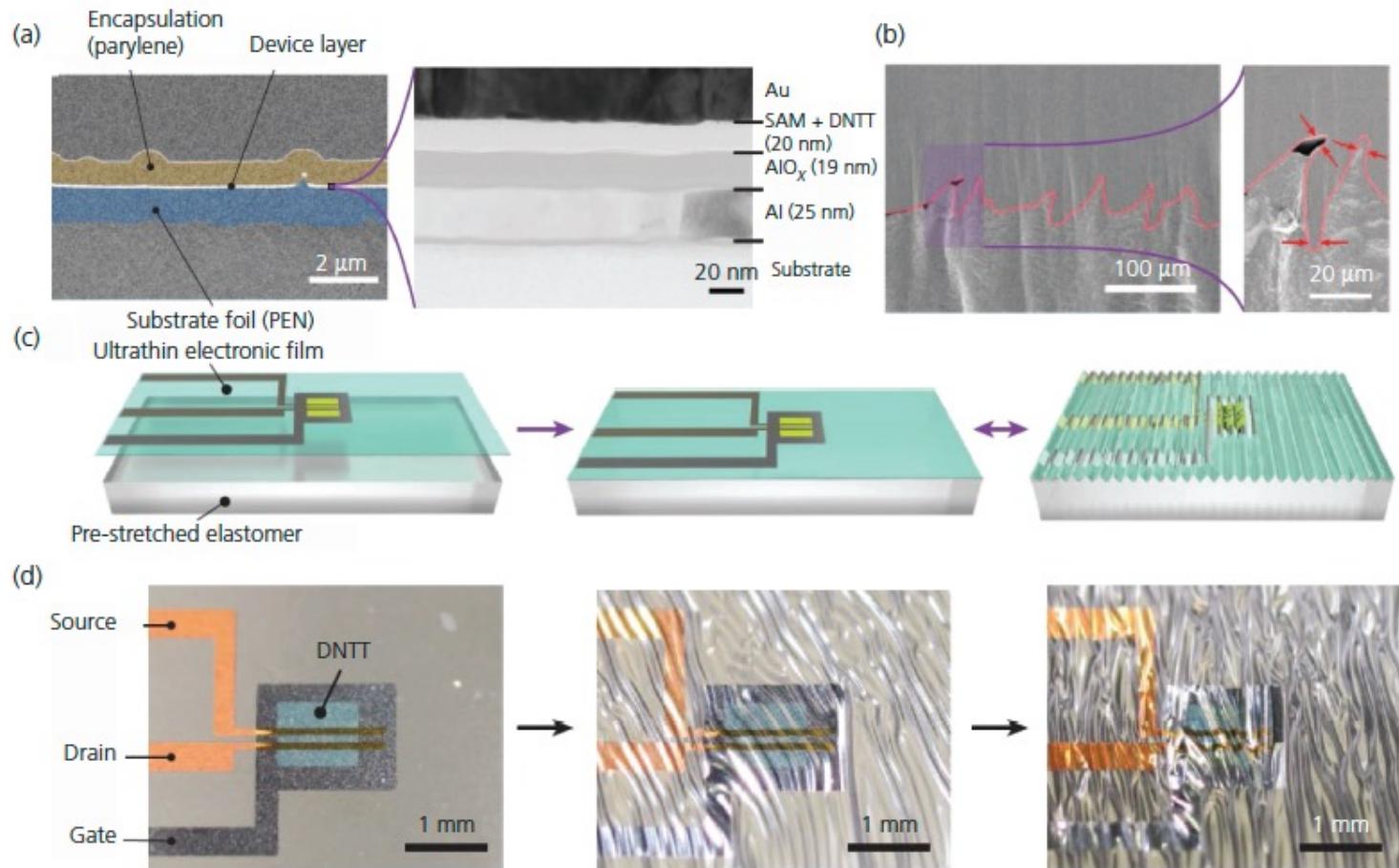
$$Y = \frac{FL_0}{A\Delta L}$$

$F$  = force to extend solid  
 $L_0$  = original length  
 $\Delta L$  = length change  
 $A$  = cross sectional area perpendicular to  $F$

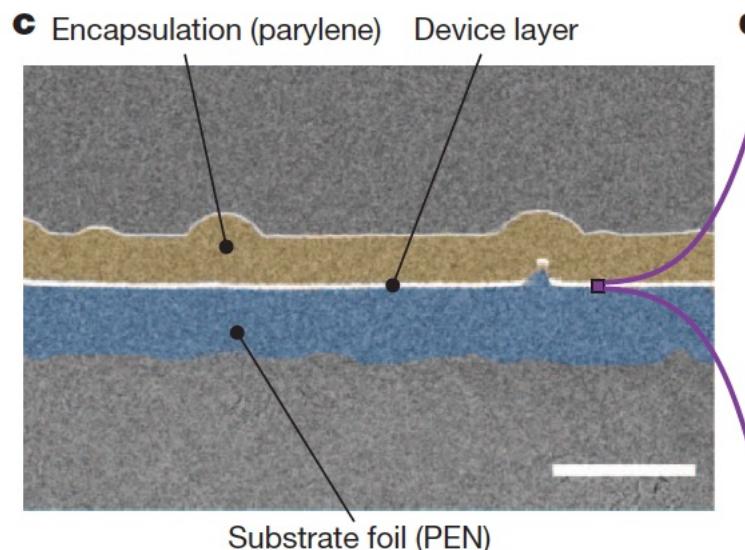
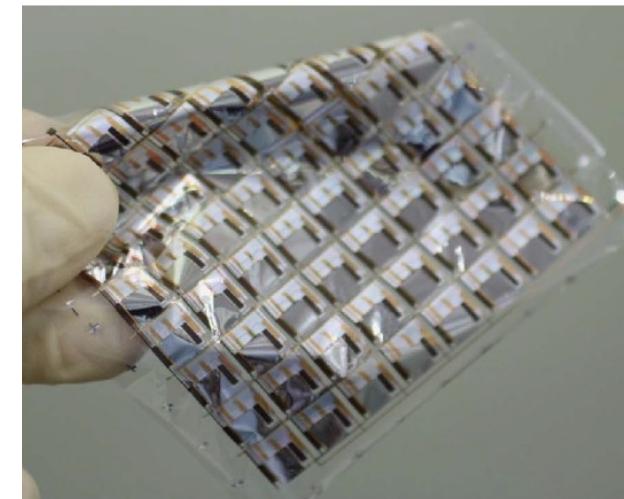
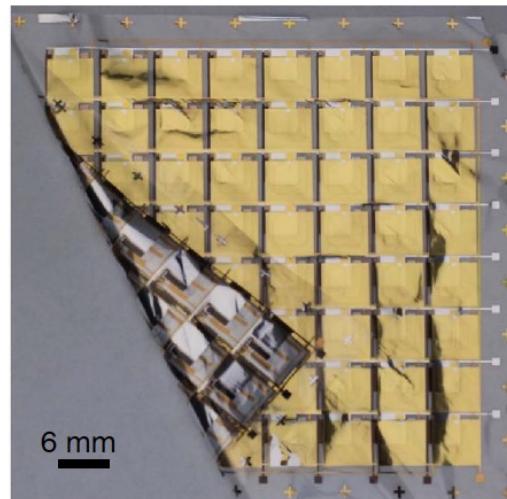
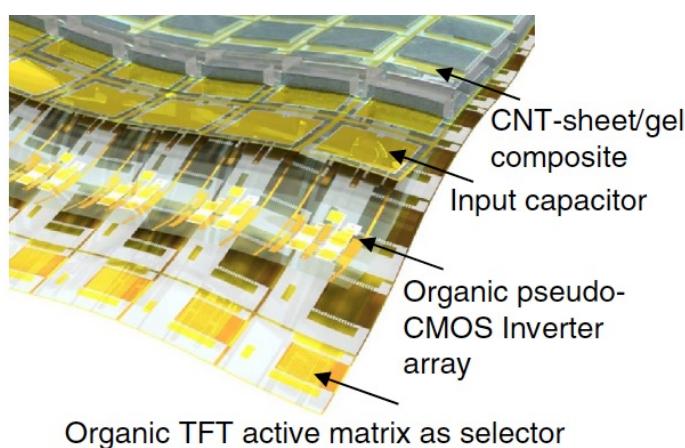


12x12 array of tactile pixels

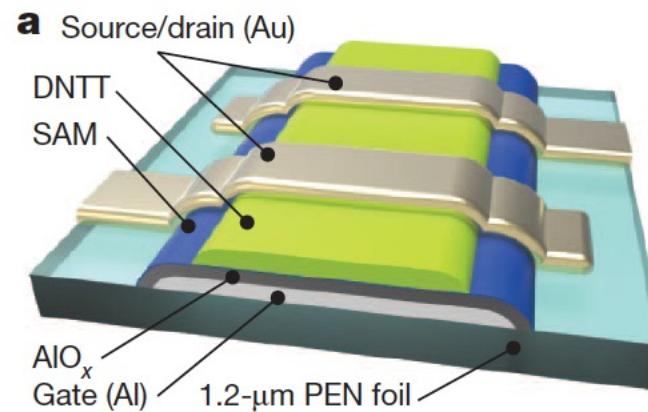
# Strain can be Built into the Substrate



# “Imperceptible” Electronics



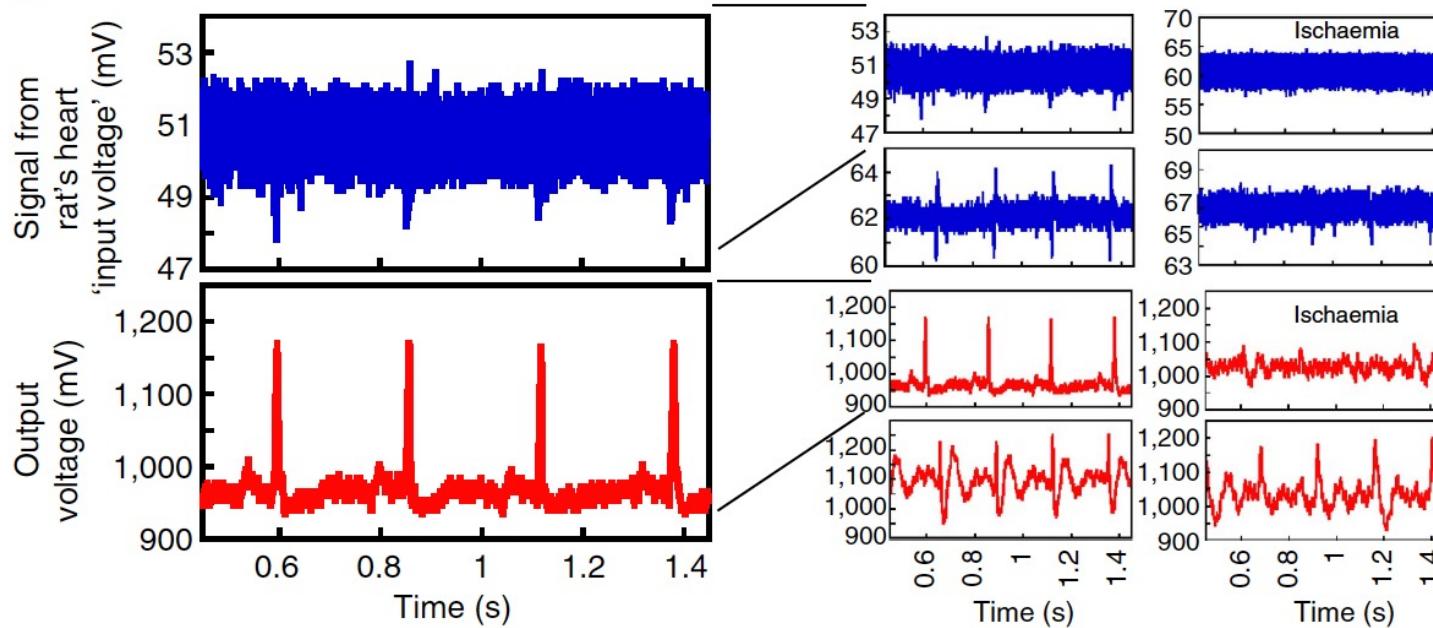
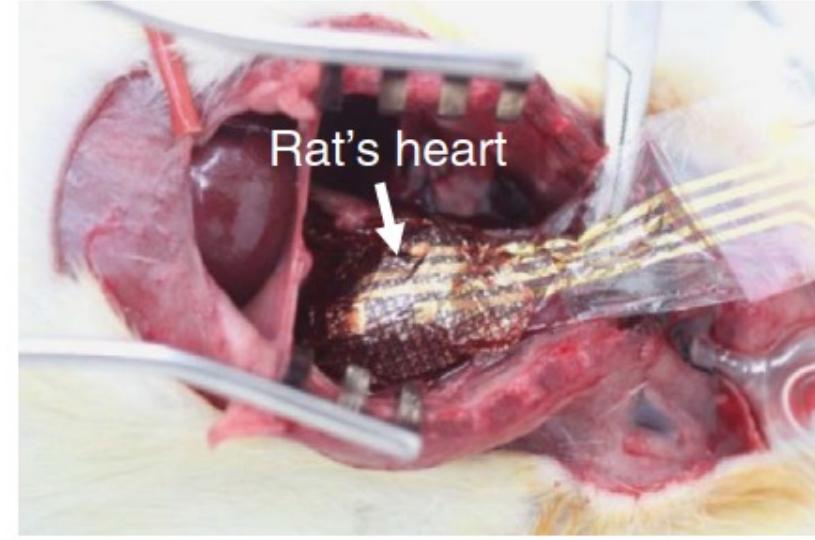
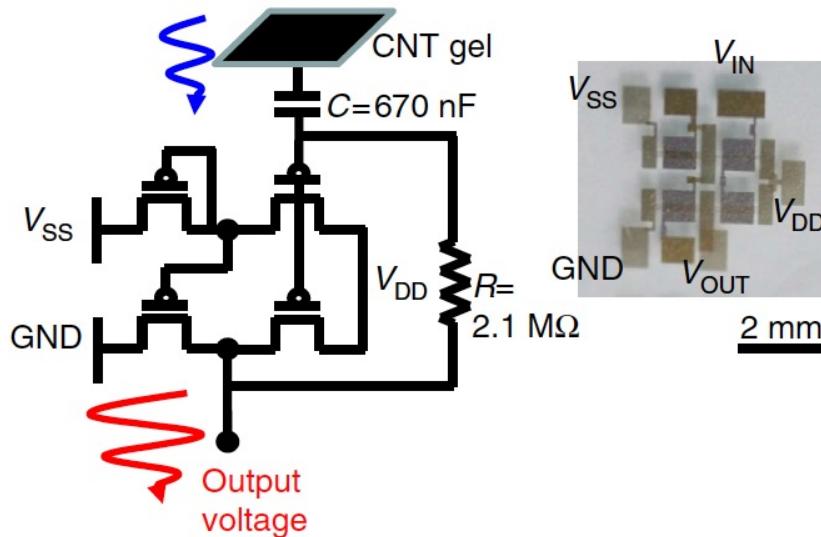
Substrates are  $1\ \mu\text{m}$  thick!



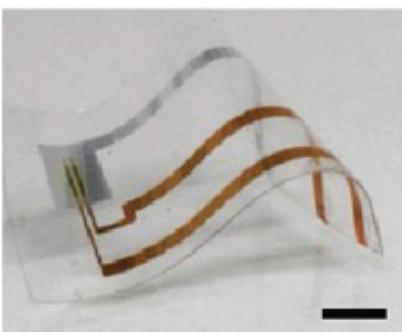
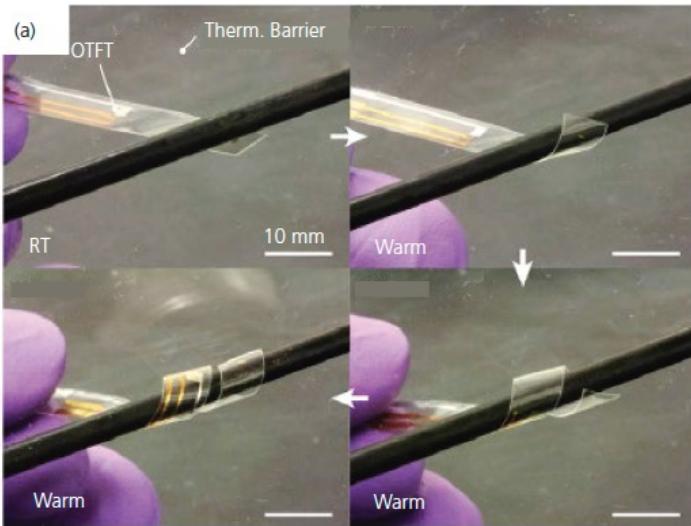
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# In Vivo Cardiac Monitoring

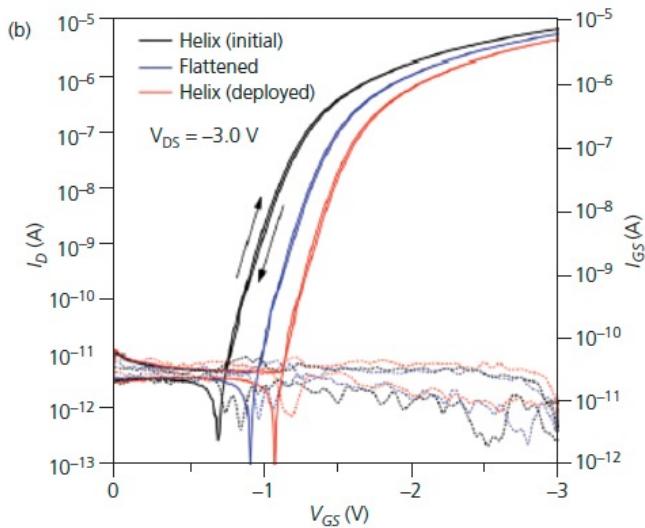
Input biosignal from the heart



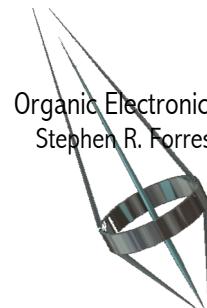
# Shape memory polymers



Shape memory: a deformed material “remembers” a previous configuration once a stimulus (e.g. temperature) is removed



- This property can be used to shape a circuit to conform to its surroundings (e.g. an organ or other structure)
- Often comprises a stressed bilayer
- In this example, the SMP is shaped to fit a wound without significant degradation of OTFT properties



# What we learned

- OTFTs have made extraordinary progress since their first demonstration in 1986
- Their properties can be modified through chemical design
- Morphology is key to high performance
- Very small gate transistors are common in BG/TC configurations
- Very large circuits demonstrated (100's of transistors)
- Reliability depends on exposure to contaminants
- Most promising applications in sensing and medicine
- But....there is no “killer app” yet identified that can drive this technology to a commercial success